

What is claimed is:

1. A method of removing adhesive film from a substrate, the adhesive film comprising first and second ends defining a length and a width transverse to the length, the method comprising:
 - applying tension over the width of the adhesive film to remove the adhesive film from the substrate along a release line;
 - distributing the tension on the substrate in the form of a compressive force; and
 - advancing the release line and the compressive force towards the second end of the adhesive film, whereby the adhesive film is removed from the substrate.
2. A method according to claim 1, wherein the compressive force is applied to the substrate along the release line.
3. A method according to claim 1, wherein the compressive force is applied to the substrate at a distance from the release line.
4. A method according to claim 3, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.
5. A method according to claim 3, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.
6. A method according to claim 3, further comprising varying the distance between the compressive force and the release line.

7. A method according to claim 6, wherein varying the distance between the compressive force and the release line comprises varying the tension applied to the adhesive film.

5 8. A method according to claim 1, wherein the compressive force is applied to the substrate by a roll.

9. A method according to claim 1, wherein applying tension over the width of the adhesive film comprises attaching the first end of the adhesive film to a
10 winding roll and winding the adhesive film thereon.

10. A method according to claim 9, wherein the compressive force is applied to the substrate by a support roll, and further wherein the winding roll and the support roll are located a fixed distance apart.

15 11. A method according to claim 1, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

12. A method of removing adhesive film from a substrate, the adhesive film
20 comprising first and second ends defining a length and a width transverse to the length, the method comprising:
attaching the first end of the adhesive film to a winding device;
rotating the winding device to apply tension over the width of the
adhesive film to remove the adhesive film from the substrate along a release line;

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advancing the release line towards the second end of the adhesive film while winding the adhesive film on the winding device, whereby the adhesive film is removed from the substrate.

30 13. A method according to claim 12, wherein the adhesive film comprises a large-scale adhesive film.

14. A method according to claim 12, further comprising distributing the tension applied to the adhesive film on the substrate in the form of a compressive force, with the compressive force being applied to the substrate by the winding device.

5 15. A method according to claim 14, wherein the compressive force is applied to the substrate along the release line.

16. A method according to claim 12, wherein the compressive force is applied to the substrate at a distance from the release line.

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17. A method according to claim 16, wherein the compressive force is applied to the substrate behind the release line as the release line advances toward the second end of the adhesive film.

15 18. A method according to claim 16, wherein the compressive force is applied to the substrate ahead of the release line as the release line advances toward the second end of the adhesive film.

19. A method according to claim 16, further comprising varying the distance
20 between the compressive force and the release line.

20. A method according to claim 19, wherein varying the distance between the compressive force and the release line comprises varying the speed at which the winding device is rotated.

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21. A method according to claim 12, further comprising heating the adhesive film before removing the adhesive film from the substrate along the release line.

22. An apparatus for removing adhesive film from a substrate, the apparatus
30 comprising:

a winding roll attached to a frame, the winding roll comprising a longitudinal axis;

a motor operably connected to the winding roll for rotating the winding roll about its longitudinal axis; and

a support roll rotatably attached to the frame, the support roll located a fixed distance from the winding roll.

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23. The apparatus of claim 22, wherein the support roll comprises an outer conformable surface.

24. The apparatus of claim 22, wherein the motor comprises a variable speed
10 motor.

25. The apparatus of claim 22, further comprising a heating device.